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Model 967 Semi-Auto Wafer Mounter



Advanced Solutions



Model 967 Semi-Auto Mounter

ADT Model 967 Semi-Auto already proven itself running successfully in production facilities worldwide. This advanced mounter provides fast, accurate and bubble-free mounting while avoiding the risks of nonuniform manual mounting. Once set, it guarantees an economic, high quality and consistent mounting for various applications.

Added value

In this article we present advanced mounting **solutions** to answer new requirements and challenges which are derived from the constantly evolving nature of our market.



ADT Model 967



Solution I Non contact wafer Mounting For MEMS & Sensitive wafers

Wafers with surface microstructures or sensitive coatings that will not tolerate force require Noncontact Mounting. The 967 Semi-Auto Mounter brings an outstanding level of consistency. This, combined with the Non-Contact features will provide a stable, bubble free mounting.





- Programmable activation positions
- Programmable mounting Velocity
- Pressure and flow settings









Solution II Thin and warped wafer Mounting For GaAs, Silicon, Germanium wafers and more

- Perforated vacuum chuck with superb finishing
- ✓ Handling tools for extremely fragile wafers
- Adjustable tape X-tension mechanism

The mechanical properties of ultra-thin semiconductor wafers such as brittleness and warpage generate difficulties in wafer handling. ADT has developed a perforated chuck with superb surface finishing. The chuck can hold down even the extremely warped GaAs wafers while keeping the wafer top surface unscratched. Combined with dedicated handling tools, we provide a proven process solution to a very challenging application.





Solution III Direct Tape Mount on wafer Support Lithography and back grinding tape Mounting

- Tape cut on the wafer edge
- ✓ Automatic Dual size support
- Non contact as an option
- ✓ Support Back grinding taping

Precision, quality and robustness are not just nice words. When it comes to our Model 967, these properties allow it to do more than what you'd expect. The direct 'Tape Mount on wafer' solution is done without the common metal frame. Immediately after a successful taping, the tape cutter accurately follows the wafer edge completing the mounting and leaving it ready for the next step.





